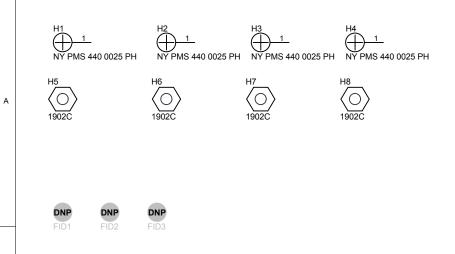
1	2	3	4	5	6
A					A
	TP1 TP2 VIN VIN	L1	R1 R2 22k 22k	MMSZ5234B-7-F 6.2V 2 2 3 4 4 2 3 4 7 5 12319DS-T1-E3	TP3 TP4 VOUT VOUT
в	Vin 8V to 32V DC TP5 TP6 + C1 - C2 GND GND - 470µF - 4.7µF - 50V	C5 0.1µF = GND 1 U1 C6	Q2 CSD19534Q5A R4 4 0 R5 N0 R5 N0 R7 0.05 GND	R3 65V @ 420mA 6.8 +C4 4700µF 80V GND TP9 OUT O	
	TP11 SD SD 47k 47k R12 47k R12 47k R12 R10	$\begin{array}{c c} & VIN & VCC \\ \hline & & 0.1 \mu F \\ \hline & & 0.1 \mu F \\ \hline & & 0.1 \mu F \\ \hline & & & 0.1 \mu F \\ \hline & & & & 0.1 \mu F \\ \hline & & & & & 0.1 \mu F \\ \hline & & & & & & 0.1 \mu F \\ \hline & & & & & & & 0.1 \mu F \\ \hline & & & & & & & & & 0.1 \mu F \\ \hline & & & & & & & & & & & & \\ \hline & & & &$		R19 ≹47 TP10 IN	
c	GND	R14 1.0k R16 1.24k	R1563.4k		c
D 1	Texas Instruments and/or its licensors do not warrant the a warrant that this design will meet the specifications, will be licensors do not warrant that the design is production worth 2	e accuracy or completeness of this specification or any information contr be suitable for your application or fit for any particular purpose, or will o rthy. You should completely validate and test your design implementation 3	ntained therein. Texas Instruments and/or its licensors do not operate in an implementation. Texas Instruments and/or its tion to confirm the system functionality for your application. 4	Orderable: N/A Designed for: Public Release   TID #: PMP20070 Project Title: LM5022 Boost   Number: PMP20070 Rev: A Sheet Title:   SVN Rev: Version control disabled Assembly Variant: 001   Drawn By: File: PMP20070 REVA.SchDoc   Engineer: R. Sheehan Contact: http://www.ti.com/support	D Mod. Date: 4/8/2016 Sheet: 1 of 2 Size: B tt C Texas INSTRUMENTS http://www.ti.com © Texas Instruments 2015 6

1	2	3	4	5	6



PCB Number: PMP20070 PCB Rev: A

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PCB PCB LOGO LOGO FCC disclaimer ESD Susceptible

Label Table				
Variant	Label Text			
001				

			C	Orderable:	N/A
			Т	ID #:	PMP20070
			N	lumber: Pl	MP20070
Texas Instruments and/or its licensors do	o not warrant the accuracy or completeness of this specification or any	information contained therein. Texas Instruments and/or its licensors do	o not S	SVN Rev:	Version contr
warrant that this design will meet the spe	cifications, will be suitable for your application or fit for any particular p	purpose, or will operate in an implementation. Texas Instruments and/or	rits D	Prawn By:	
licensors do not warrant that the design is	s production worthy. You should completely validate and test your des	ign implementation to confirm the system functionality for your application	on. E	ingineer: F	R. Sheehan
	2	4			
2	3	4			

C

	Designed for: Public Release	Mod. Date: 2/25/2016	
)	Project Title: LM5022 Boost	TEXAS	
Rev: A	Sheet Title:		
ntrol disabled	Assembly Variant: 001	Sheet: 2 of 2	In Office Meli (15
	File: PMP20070 REVA Hardware.Sch	Doc Size: B	http://www.ti.com
	Contact: http://www.ti.com/support	© Texas Instruments 2015	
5		6	

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